

N-Channel Power MOSFET

700V, 8A, 0.6Ω

FEATURES

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance

| DI I | CA | TI | ON |
|------|----|----|----|

- Power Supply
- Lighting

| KEY PERFORMANCE PARAMETERS | | | | |
|----------------------------|------|----|--|--|
| PARAMETER VALUE UNIT | | | | |
| V _{DS} | 700 | V | | |
| R _{DS(on)} (max) | 0.6 | Ω | | |
| Q_g | 12.6 | nC | | |



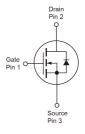












Notes: Moisture sensitivity level: level 3. Per J-STD-020

| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | | |
|---|------------------------|-----------------------------------|--------------|-----------|------|--|
| PARAMETER | | SYMBOL | ITO-220 | IPAK/DPAK | UNIT | |
| Drain-Source Voltage | | V _{DS} | 700 | | V | |
| Gate-Source Voltage | | V _{GS} | ±30 | | V | |
| Continuous Drain Current (Note 1) | $T_C = 25^{\circ}C$ |] , [| 8 4.8 | | А | |
| Continuous Drain Current | T _C = 100°C | | | | | |
| Pulsed Drain Current (Note 2) | | I _{DM} | 24 | | А | |
| Total Power Dissipation @ T _C = 25°C | | P _{DTOT} | 32 | 83 | W | |
| Single Pulsed Avalanche Energy (Note 3) | | E _{AS} | 100 | | mJ | |
| Single Pulsed Avalanche Current (Note 3) | | I _{AS} | 2 | | А | |
| Operating Junction and Storage Temperature Range | | T _J , T _{STG} | - 55 to +150 | | °C | |

| THERMAL PERFORMANCE | | | | | |
|--|------------------|---------|-----------|------|--|
| PARAMETER | SYMBOL | ITO-220 | IPAK/DPAK | UNIT | |
| Junction to Case Thermal Resistance | R _{eJC} | 3.9 | 1.5 | °C/W | |
| Junction to Ambient Thermal Resistance | $R_{\Theta JA}$ | 62 | | °C/W | |

Notes: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JA}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. $R_{\Theta JA}$ shown below for single device operation on FR-4 PCB in still air.



| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | | |
|---|---|---------------------|-----|-------|------|------|
| PARAMETER | CONDITIONS | SYMBOL | MIN | TYP | MAX | UNIT |
| Static (Note 4) | | | | | | |
| Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | BV _{DSS} | 700 | | | V |
| Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | $V_{GS(TH)}$ | 2 | 2.9 | 4 | V |
| Gate Body Leakage | $V_{GS} = \pm 30V, V_{DS} = 0V$ | I _{GSS} | | | ±100 | nA |
| Zero Gate Voltage Drain Current | $V_{DS} = 700V, V_{GS} = 0V$ | I _{DSS} | | | 1 | μΑ |
| Drain-Source On-State Resistance | $V_{GS} = 10V, I_D = 4A$ | R _{DS(on)} | | 0.5 | 0.6 | Ω |
| Dynamic (Note 5) | | | | | | |
| Total Gate Charge | ., | Q_g | | 12.6 | | |
| Gate-Source Charge | $V_{DS} = 380V, I_{D} = 8A,$ | Q_gs | | 2.9 | | nC |
| Gate-Drain Charge | $V_{GS} = 10V$ | Q_{gd} | | 4.5 | | |
| Input Capacitance | $V_{DS} = 100V, V_{GS} = 0V,$ | C _{iss} | | 743 | | . = |
| Output Capacitance | f = 1.0MHz | C _{oss} | | 63 | | pF |
| Gate Resistance | F = 1MHz, open drain | R_g | | 3.19 | | Ω |
| Switching (Note 6) | | | | | | |
| Turn-On Delay Time | | t _{d(on)} | | 21 | | |
| Turn-On Rise Time | $V_{DD} = 380V,$ $R_{GEN} = 25\Omega,$ $I_{D} = 8A, V_{GS} = 10V,$ | t _r | | 15 | | |
| Turn-Off Delay Time | | t _{d(off)} | | 40 | | ns |
| Turn-Off Fall Time | $\int_{\mathbb{R}^{n}} \mathcal{G}(x) ^{2} dx = \int_{\mathbb{R}^{n}} \mathcal{G}(x) ^{2} dx$ | t _f | | 9 | | |
| Source-Drain Diode (Note 4) | | | | | | |
| Forward On Voltage | $I_{S} = 8A, V_{GS} = 0V$ | V_{SD} | - | 0.84 | 1.4 | V |
| Reverse Recovery Time | V _R =200V, I _S = 4A | t _{rr} | | 187.9 | | ns |
| Reverse Recovery Charge | $dI_F/dt = 100A/\mu s$ | Q _{rr} | 1 | 1.4 | | μC |

Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 50mH, $I_{AS} = 2A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$
- 4. Pulse test: PW \leq 300 μ s, duty cycle \leq 2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.





ORDERING INFORMATION

| PART NO. | PACKAGE | PACKING |
|-----------------|---------------|---------------------|
| TSM70N600CI C0G | ITO-220 | 50pcs / Tube |
| TSM70N600CH C5G | TO-251 (IPAK) | 75pcs / Tube |
| TSM70N600CP ROG | TO-252 (DPAK) | 2,500pcs / 13" Reel |

Note:

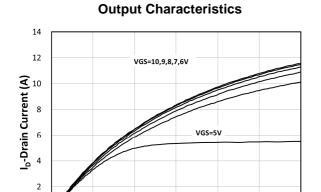
- 1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- 2. Halogen-free according to IEC 61249-2-21 definition



0 0

CHARACTERISTICS CURVES

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

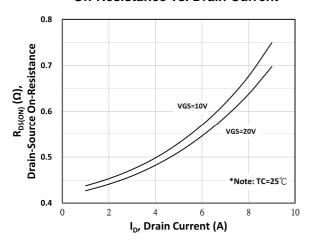


On-Resistance vs. Drain Current

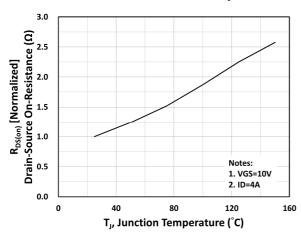
V_{DS}-Drain to Source Voltage (V)

VGS=4V

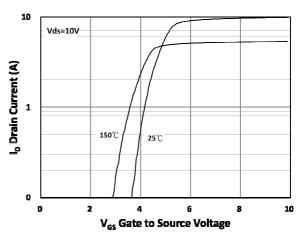
10



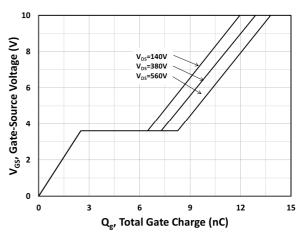
On-Resistance vs. Junction Temperature



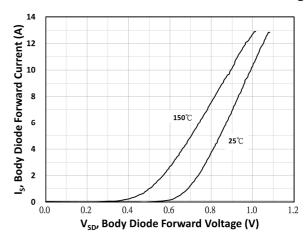
Transfer Characteristics



Gate-Source Voltage vs. Gate Charge



Source-Drain Diode Forward Current vs. Voltage

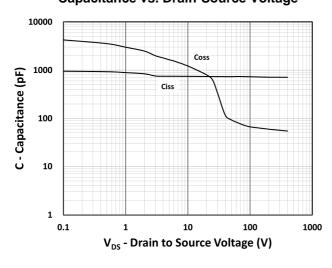




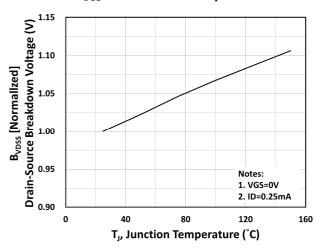
CHARACTERISTICS CURVES

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

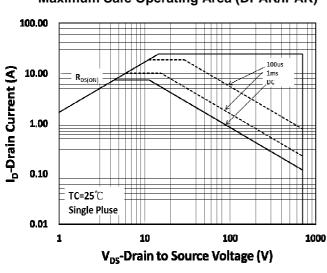
Capacitance vs. Drain-Source Voltage



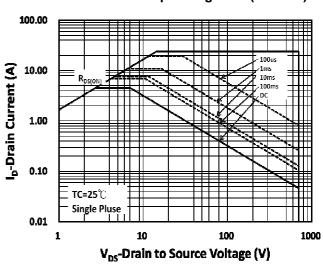
BV_{DSS} vs. Junction Temperature



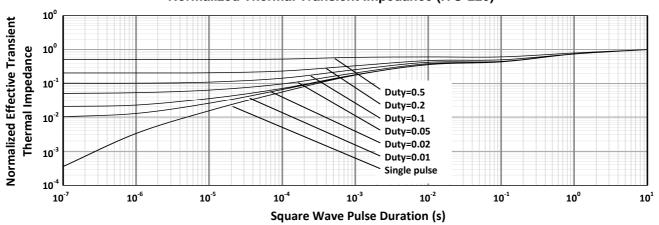
Maximum Safe Operating Area (DPAK/IPAK)



Maximum Safe Operating Area (ITO-220)



Normalized Thermal Transient Impedance (ITO-220)

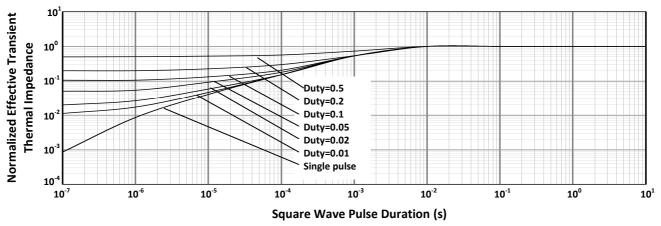




ELECTRICAL CHARACTERISTICS CURVES

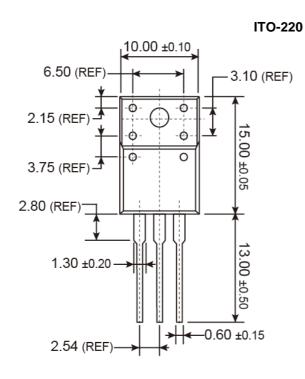
 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

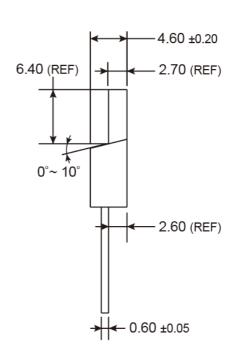
Normalized Thermal Transient Impedance (DPAK/IPAK)





PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)





MARKING DIAGRAM



G = Halogen Free

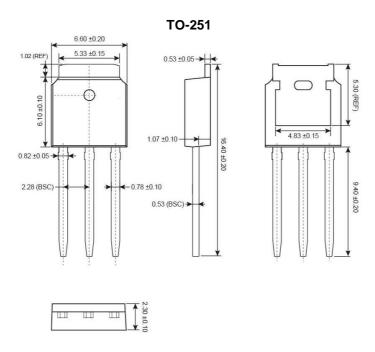
Y = Year Code

WW = Week Code (01~52)

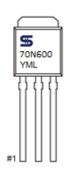
F = Factory Code



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

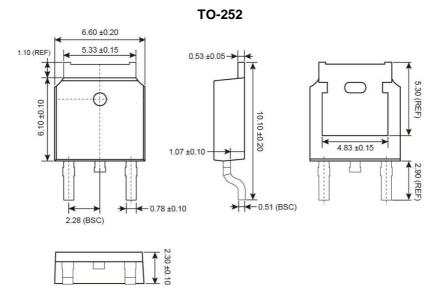
O =Jan P =Feb Q =Mar R =Apr S =May T =Jun U =Jul V =Aug

W = Sep X = Oct Y = Nov Z = Dec

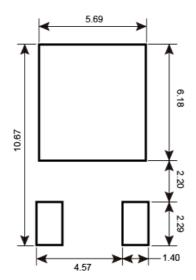
L = Lot Code (1~9, A~Z)



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

O =Jan P =Feb Q =Mar R =Apr

S =May T =Jun U =Jul V =Aug

W = Sep X = Oct Y = Nov Z = Dec

L = Lot Code (1~9, A~Z)



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